

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 10-168409

(43)Date of publication of application : 23.06.1998

(51)Int.Cl.

C09J 7/02
B32B 15/08
C09J179/08
C09J183/00
H01L 23/50

(21)Application number : 08-335529

(71)Applicant : HITACHI CHEM CO LTD

(22)Date of filing : 16.12.1996

(72)Inventor : HOSOKAWA YOICHI
NOMURA YOSHIHIRO
KIRIHARA HIROSHI
TANABE YOSHIYUKI
IIOKA SHINJI
YANAGISAWA SATOSHI

(54) COPPER FOIL COATED WITH HEAT-RESISTANT ADHESIVE LAYER, AND LEAD FRAME FITTED WITH HEAT DISSIPATION PLATE AND SEMICONDUCTOR DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a resin-sealed semiconductor device capable of being produced by a simplified step of producing a heat spreader, excellent in electrical properties and free from reflow cracking.

SOLUTION: This invention provides a copper foil coated with a heat-resistant adhesive layer, prepared by forming a layer of an adhesive of a heat-resistant resin composition containing 10-80wt.%, based on the heat-resistant resin, silicone rubber filler having surface epoxy or amido groups, 0.5-10wt.% organic solvent, 0.5-20wt.% crosslinking agent and at least one heat-resistant resin selected among aromatic polyamides, aromatic polyimides, aromatic polyamide imides, aromatic polyether amides, aromatic polyether imides and aromatic polyether amide imides on either surface of a 50-200µm thick copper foil and a lead frame and a semiconductor using the foil.

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]